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# Low-Voltage CMOS Quad 2-Input Multiplexer

With 5 V–Tolerant Inputs (Non–Inverting)

# MC74LCX157A

The MC74LCX157A is a high performance, quad 2-input multiplexer operating from a 1.65 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V<sub>I</sub> specification of 5.5 V allows MC74LCX157A inputs to be safely driven from 5 V devices.

Four bits of data from two sources can be selected using the Select and Enable inputs. The four outputs present the selected data in the true (non-inverted) form. The MC74LCX157A can also be used as a function generator. Current drive capability is 24 mA at the outputs.

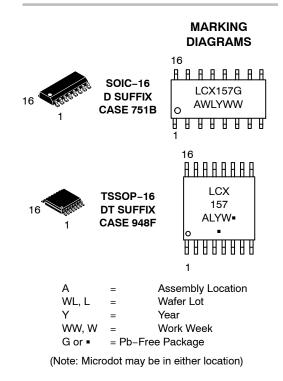
# Features

- Designed for 1.65 to 3.6 V  $V_{CC}$  Operation
- 5 V Tolerant Inputs Interface Capability With 5 V TTL Logic
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current (10 µA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 100 mA
- ESD Performance:
  - ♦ Human Body Model >2000 V
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



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# **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

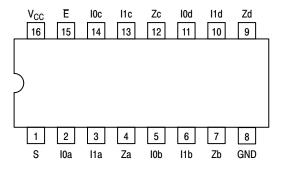
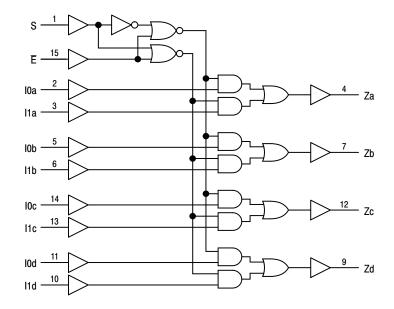


Figure 1. 16-Lead Pinout (Top View)

PI	ΝN	ΙΔΝ	<b>IES</b>

Pins	Function			
l0n	Source 0 Data Inputs			
l1n	Source 1 Data Inputs			
Ē	Enable Input			
S	Select Input			
Zn	Outputs			





### **TRUTH TABLE**

Inputs			Outputs	
Ē	S	l0n	l1n	Zn
HLLL	X H H L L	ХХХГТ	X L H X X	ТГТГ

H = High Voltage Level; L = Low Voltage Level; X = High or Low Voltage Level ; For I<sub>CC</sub> Reasons DO NOT FLOAT Inputs

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC74LCX157ADR2G (Contact ON Semiconductor)	SOIC-16 (Pb-Free)	2500 Tape & Reel
MC74LCX157ADTR2G	TSSOP-16 (Pb-Free)	2500 Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### **Table 1. MAXIMUM RATINGS**

Symbol	Parameter		Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +6.5	V
VI	DC Input Voltage (Note 1)		–0.5 to +6.5	V
Vo	DC Output Voltage (Note 1)	Active-Mode (High or Low State) Tri-State Mode Power-Down Mode (V <sub>CC</sub> = 0 V)	-0.5 to V <sub>CC</sub> + 0.5 -0.5 to +6.5 -0.5 to +6.5	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < GND	-50	mA
I <sub>OK</sub>	DC Output Diode Current	V <sub>OUT</sub> < GND	-50	mA
Ι <sub>Ο</sub>	DC Output Source/Sink Current		±50	mA
I <sub>CC</sub>	DC Supply Current Per Supply Pin		±100	mA
I <sub>GND</sub>	DC Supply Current Per Ground Pin		±100	mA
T <sub>STG</sub>	Storage Temperature Range		–65 to +150	°C
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage (Note 2)	Human Body Model Charged Device Model	> 2000 N/A	V
ILATCHUP	Latchup Performance (Note 3)		±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Io absolute maximum rating must be observed.
HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.
Tested to EIA/JESD78 Class II.

# Table 2. RECOMMENDED OPERATING CONDITIONS

Symbol	Paran	neter	Min	Тур	Max	Unit
V <sub>CC</sub>	Supply Voltage	Operating	1.65	3.3	3.6	V
		Data Retention Only	1.5	3.3	3.6	
VI	Digital Input Voltage		0	-	5.5	V
Vo	Output Voltage	Active Mode (High or Low State)	0	-	V <sub>CC</sub>	V
		Tri-State Mode	0	-	5.5	
		Power Down Mode ( $V_{CC} = 0 V$ )	0	-	5.5	
T <sub>A</sub>	Operating Free-Air Temperature		-40	-	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Transition Rise or Fall Rate $V_{I}$ = from 0.8 V to 2.0 V, $V_{CC}$ = 3.0 V	/	0	-	10	nS/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

# Table 3. DC ELECTRICAL CHARACTERISTICS

				$T_A = -40^\circ$	C to +85°C	$T_A = -40^{\circ}C$	C to +125°C	
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	Min	Max	Min	Max	Unit
V <sub>IH</sub>	High-Level Input		1.65 to 1.95	0.65 x V <sub>CC</sub>	-	0.65 x V <sub>CC</sub>	-	V
	Voltage		2.3 to 2.7	1.7	-	1.7	-	
			2.7 to 3.6	2.0	-	2.0	-	
V <sub>IL</sub>	Low-Level Input		1.65 to 1.95	-	0.35 x V <sub>CC</sub>	-	0.35 x V <sub>CC</sub>	V
	Voltage		2.3 to 2.7	-	0.7	-	0.7	
			2.7 to 3.6	-	0.8	-	0.8	
V <sub>OH</sub>	High-Level	$V_I = V_{IH} \text{ or } V_{IL}$						V
	Output Voltage	I <sub>OH</sub> = -100 μA	1.65 to 3.6	$V_{CC}-0.2$	-	V <sub>CC</sub> - 0.2	-	
		$I_{OH} = -4 \text{ mA}$	1.65	1.2	-	1.2	-	
		I <sub>OH</sub> = -8 mA	2.3	1.8	-	1.8	-	
		I <sub>OH</sub> = -12 mA	2.7	2.2	-	2.2	-	
		I <sub>OH</sub> = -16 mA	3.0	2.4	-	2.4	-	
		I <sub>OH</sub> = -24 mA	3.0	2.2	-	2.2	-	
V <sub>OL</sub>	Low-Level	$V_I = V_{IH} \text{ or } V_{IL}$						V
	Output Voltage	I <sub>OL</sub> = 100 μA	1.65 to 3.6	-	0.2	-	0.2	
		I <sub>OL</sub> = 4 mA	1.65	-	0.45	-	0.45	
		I <sub>OL</sub> = 8 mA	2.3	-	0.6	-	0.6	
		I <sub>OL</sub> = 12 mA	2.7	-	0.4	-	0.4	
		I <sub>OL</sub> = 16 mA	3.0	-	0.4	-	0.4	
		I <sub>OL</sub> = 24 mA	3.0	-	0.55	-	0.6	
lı	Input Leakage Current	V <sub>I</sub> = 0 to 5.5 V	3.6	-	±5.0	-	±5.0	μΑ
I <sub>OFF</sub>	Power Off Leakage Current	$V_{I} = 5.5 V \text{ or}$ $V_{O} = 5.5 V$	0	-	10	-	20	μA
I <sub>CC</sub>	Quiescent Supply Current	V <sub>I</sub> = 5.5 V or GND	3.6	-	10	-	10	μA
$\Delta I_{CC}$	Increase in I <sub>CC</sub> per Input	$V_{IH} = V_{CC} - 0.6 V$	2.3 to 3.6	_	500	-	500	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# Table 4. AC ELECTRICAL CHARACTERISTICS

				$T_A = -40^\circ$	C to +85°C	$T_A = -40^{\circ}C$	to +125°C	
Symbol	Parameter	Test Condition	V <sub>CC</sub> (V)	Min	Max	Min	Max	Unit
t <sub>PLH</sub> ,	Propagation Delay,	See Figures 3 and 4	1.65 to 1.95	-	11.4	-	11.4	ns
t <sub>PHL</sub>	In to Zn		2.3 to 2.7	-	8.7	-	8.7	
			2.7	-	6.3	-	6.3	
			3.0 to 3.6	-	5.8	-	5.8	
t <sub>PLH</sub> ,	Propagation Delay, S to Zn		1.65 to 1.95	-	13.0	-	13.0	ns
t <sub>PHL</sub>		2.3 to 2.7	-	9.0	-	9.0		
			2.7	_	8.0	-	8.0	
			3.0 to 3.6	-	7.0	-	7.0	
t <sub>PLH</sub> , Propagation Delay,		See Figures 3 and 4	1.65 to 1.95	-	13.0	-	13.0	ns
t <sub>PHL</sub>	to Zn		2.3 to 2.7	-	9.0	-	9.0	
			2.7	-	8.0	-	8.0	
			3.0 to 3.6	-	7.0	-	7.0	

# Table 5. DYNAMIC SWITCHING CHARACTERISTICS

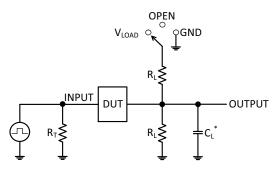
				T <sub>A</sub> = +25°C			
Symbol	Parameter	Test Condition	V <sub>CC</sub> (V)	Min	Тур	Мах	Unit
V <sub>OLP</sub>	Dynamic LOW Peak Voltage (Note 4)	$C_L$ = 50 pF, $V_{IH}$ = 3.3 V, $V_{IL}$ = 0 V	3.3	-	0.8	-	V
V <sub>OLV</sub>	Dynamic LOW Valley Voltage (Note 4)	$C_{L}$ = 50 pF, $V_{IH}$ = 3.3 V, $V_{IL}$ = 0 V	3.3	-	-0.8	-	V

4. Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

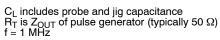
# Table 6. CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Test Condition	Typical (T <sub>A</sub> = 25°C)	Unit
C <sub>IN</sub>	Input Capacitance	$V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	7	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	8	
C <sub>PD</sub>	Power Dissipation Capacitance (Note 5)	10 MHz, $V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	25	

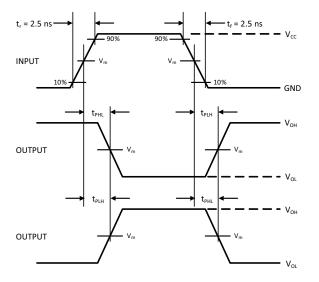
5. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation I<sub>CC(OPR)</sub> = C<sub>PD</sub> x V<sub>CC</sub> x f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no-load dynamic power consumption: P<sub>D</sub> = C<sub>PD</sub> x V<sub>CC</sub><sup>2</sup> x f<sub>in</sub> + I<sub>CC</sub> x V<sub>CC</sub>.

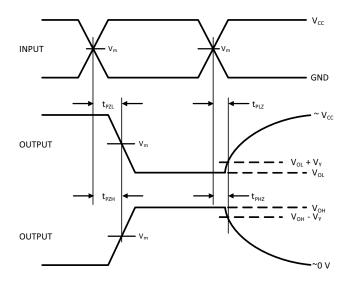


Test	Switch Position
t <sub>PLH</sub> / t <sub>PHL</sub>	Open
t <sub>PLZ</sub> / t <sub>PZL</sub>	V <sub>LOAD</sub>
t <sub>PHZ</sub> / t <sub>PZH</sub>	GND







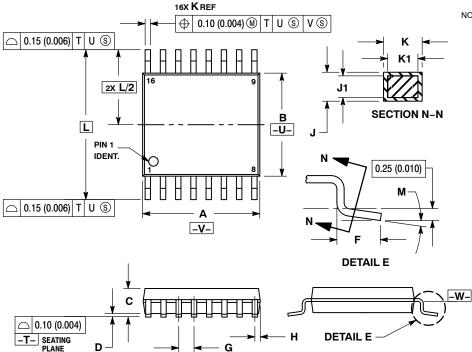


# Figure 4. Switching Waveforms

V <sub>CC</sub> , V	$R_{L}, \Omega$	C <sub>L</sub> , pF	V <sub>LOAD</sub>	V <sub>m</sub> , V	V <sub>Y</sub> , V
1.65 to 1.95	500	30	$2 \times V_{CC}$	V <sub>CC</sub> /2	0.15
2.3 to 2.7	500	30	$2 \times V_{CC}$	V <sub>CC</sub> /2	0.15
2.7	500	50	6 V	1.5	0.3
3.0 to 3.6	500	50	6 V	1.5	0.3

# PACKAGE DIMENSIONS

TSSOP-16 **DT SUFFIX** CASE 948F **ISSUE B** 



G

NOTES:

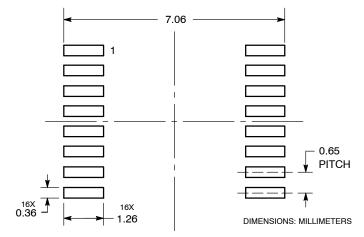
DTES:
DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
CONTROLLING DIMENSION: MILLIMETER.
DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08

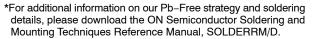
DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL

CONDITION. 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

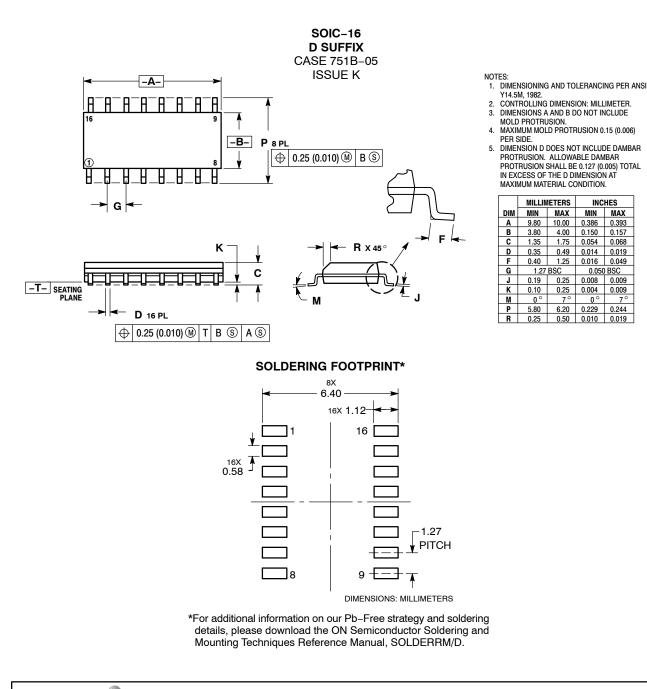
	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
Н	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
К	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
Μ	0 °	8 °	0 °	8 °

### **SOLDERING FOOTPRINT\***





## PACKAGE DIMENSIONS



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